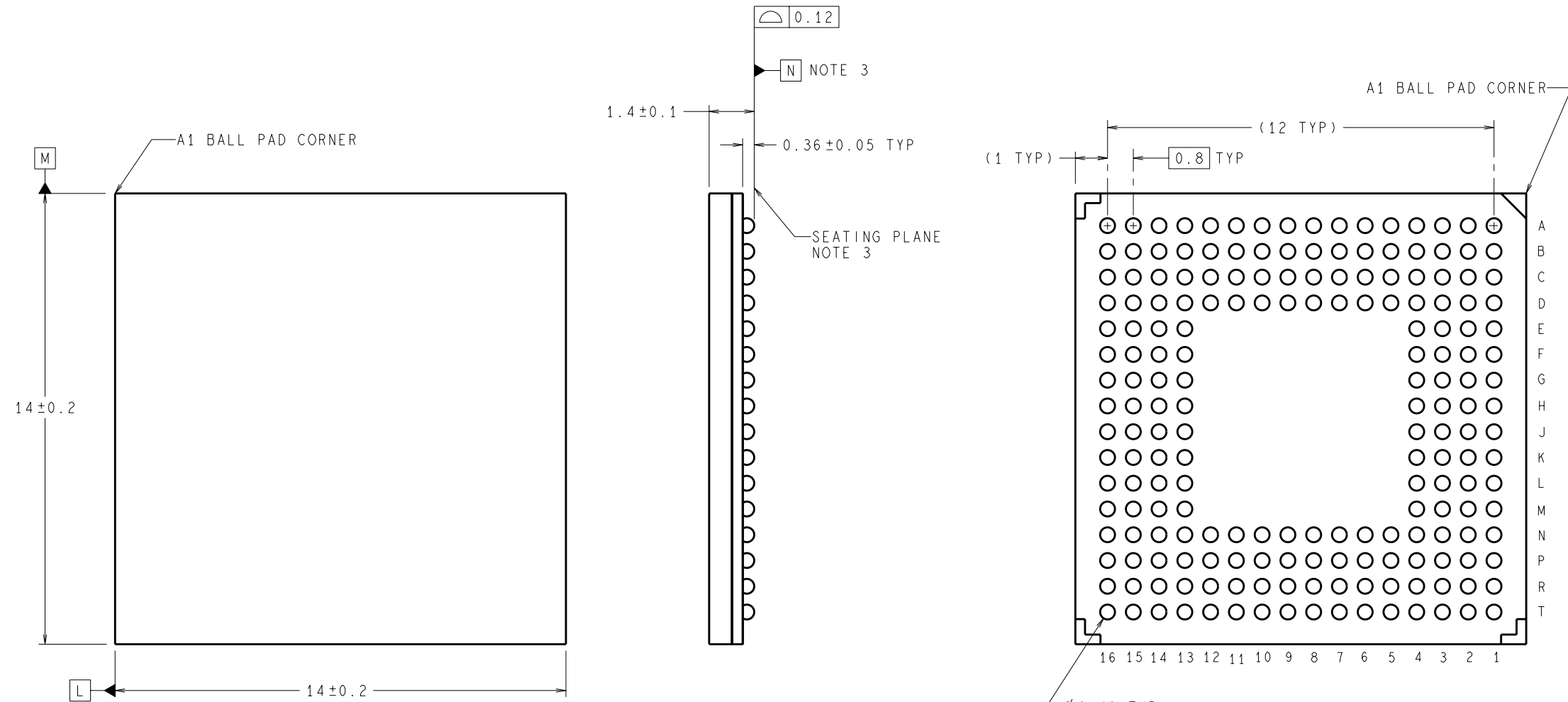


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12446	04/17/2000	TL/SL



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF APRIL 2000.

\varnothing	0.15	M	N	L	S	M	S
\varnothing	0.08	M	N				

APPROVALS	DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN T. LEQUANG	04/18/2000	FBGA, PLASTIC, LAMINATED, 14 X 14 X 1.4mm BODY, 192 BALL, 0.8mm PITCH			
DFTG. CHK. MARTA SUCHY	04/18/2000				
ENGR. CHK. SHAW LEE	04/18/2000				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV	
	N/A	C	(SC)MKT-SLC192A	A	
DO NOT SCALE DRAWING				SHEET 1 of 1	